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(71) Applicant *(for all designated States except US)*: **INTEL CORPORATION** [US/US]; 2200 Mission College Blvd., Santa Clara, California 95052 (US).

(72) Inventor; and

(75) Inventor/Applicant *(for US only)*: **HUA, Fay** [US/US]; 626 Bella Vista Ct., Fremont, California 94539 (US).

(74) Agents: **MCCRACKIN, Ann M** et al.; Schwegman, Lundberg, Woessner & Kluth, P.A., P.O. Box 2938, Minneapolis, Minnesota 55402 (US).

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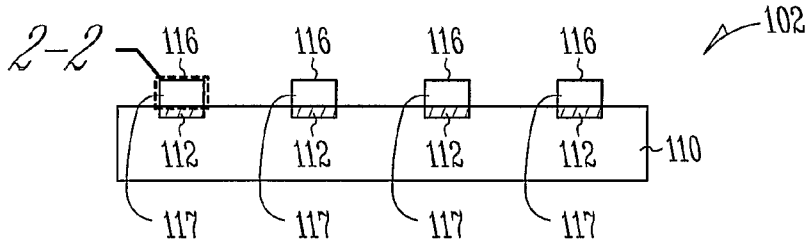
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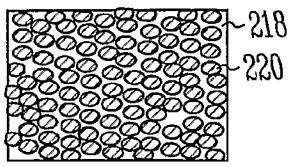
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(54) Title: ELECTROMIGRATION-RESISTANT AND COMPLIANT WIRE INTERCONNECTS, NANO-SIZED SOLDER COMPOSITIONS, SYSTEMS MADE THEREOF, AND METHODS OF ASSEMBLING SOLDERED PACKAGES





(57) Abstract: A nano-sized metal particle composite includes a first metal that has a particle size of about 50 nanometer or smaller. A wire interconnect is in contact with a reflowed nanosolder and has the same metal or alloy composition as the reflowed nanosolder. A microelectronic package is also disclosed that uses the reflowed nanosolder composition. A method of assembling a microelectronic package includes preparing a wire interconnect template. A computing system includes a nanosolder composition coupled to a wire interconnect.

WO 2007/005592 A3